

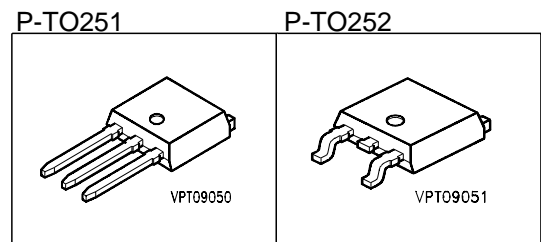
Cool MOS™ Power Transistor

Feature

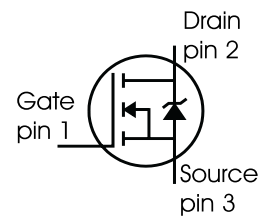
- New revolutionary high voltage technology
- Ultra low gate charge
- Periodic avalanche rated
- Extreme dv/dt rated
- High peak current capability
- Improved transconductance
- 150 °C operating temperature

Product Summary

$V_{DS} @ T_{jmax}$	650	V
$R_{DS(on)}$	1.4	Ω
I_D	3.2	A



Type	Package	Ordering Code	Marking
SPD03N60C3	P-TO252	Q67040-S4421	03N60C3
SPU03N60C3	P-TO251	-	03N60C3



Maximum Ratings, at $T_C = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Continuous drain current $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	I_D	3.2 2	A
Pulsed drain current, t_p limited by T_{jmax}	$I_{D\ puls}$	9.6	
Avalanche energy, single pulse $I_D=1.6\text{A}, V_{DD}=50\text{V}$	E_{AS}	100	mJ
Avalanche energy, repetitive t_{AR} limited by T_{jmax} ¹⁾ $I_D=3.2\text{A}, V_{DD}=50\text{V}$	E_{AR}	0.2	
Avalanche current, repetitive t_{AR} limited by T_{jmax}	I_{AR}	3.2	A
Reverse diode dv/dt $I_S=3.2\text{A}, V_{DS} < V_{DD}, di/dt=100\text{A}/\mu\text{s}, T_{jmax}=150^\circ\text{C}$	dv/dt	6 -	V/ns
Gate source voltage static	V_{GS}	± 20	V
Gate source voltage AC ($f > 1\text{Hz}$)	V_{GS}	± 30	
Power dissipation, $T_C = 25^\circ\text{C}$	P_{tot}	38	W
Operating and storage temperature	T_j, T_{stg}	-55... +150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Thermal resistance, junction - case	R_{thJC}	-	-	3.3	K/W
Thermal resistance, junction - ambient, leaded	R_{thJA}	-	-	75	
SMD version, device on PCB: @ min. footprint @ 6 cm ² cooling area ²⁾	R_{thJA}	-	-	75 50	
Linear derating factor		-	-	0.3	W/K
Soldering temperature, 1.6 mm (0.063 in.) from case for 10s	T_{sold}	-	-	260	°C

Electrical Characteristics, at $T_j = 25\text{ °C}$, unless otherwise specified

Static Characteristics

Drain-source breakdown voltage $V_{GS}=0V, I_D=0.25mA$	$V_{(BR)DSS}$	600	-	-	V
Drain-source avalanche breakdown voltage $V_{GS}=0V, I_D=3.2A$	$V_{(BR)DS}$	-	700	-	
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D = 135\text{ }\mu A$	$V_{GS(th)}$	2.1	3	3.9	
Zero gate voltage drain current $V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}, T_j = 25\text{ °C}$ $V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}, T_j = 150\text{ °C}$	I_{DSS}	-	0.5	1	μA
		-	-	70	
Gate-source leakage current $V_{GS}=30V, V_{DS}=0V$	I_{GSS}	-	-	100	nA
Drain-source on-state resistance $V_{GS}=10V, I_D=2A, T_j=25\text{ °C}$ $V_{GS}=10V, I_D=2A, T_j=150\text{ °C}$	$R_{DS(on)}$	-	1.26	1.4	Ω
		-	2.6	2.9	
Gate input resistance $f = 1\text{ MHz}$, open drain	R_G	-	10	-	

¹ Repetitive avalanche causes additional power losses that can be calculated as $P_{AV} = E_{AR} \cdot f$.

² Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical without blown air.

Electrical Characteristics , at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Characteristics						
Transconductance	g_{fs}	$V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$ $I_D = 2A$	-	3.4	-	S
Input capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V,$	-	400	-	pF
Output capacitance	C_{oss}	$f = 1MHz$	-	150	-	
Reverse transfer capacitance	C_{rss}		-	5	-	
Effective output capacitance, 1) energy related	$C_{o(er)}$	$V_{GS} = 0V,$ $V_{DS} = 0V \text{ to } 480V$	-	12	-	pF
Effective output capacitance, 2) time related	$C_{o(tr)}$		-	26	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 350V, V_{GS} = 0/10V,$	-	7	-	ns
Rise time	t_r	$I_D = 3.2A, R_G = 20\Omega$	-	3	-	
Turn-off delay time	$t_{d(off)}$		-	64	100	
Fall time	t_f		-	12	20	

Gate Charge Characteristics

Gate to source charge	Q_{gs}	$V_{DD} = 420V, I_D = 3.2A$	-	2	-	nC
Gate to drain charge	Q_{gd}		-	6	-	
Gate charge total	Q_g	$V_{DD} = 420V, I_D = 3.2A,$ $V_{GS} = 0 \text{ to } 10V$	-	13	17	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} = 420V, I_D = 3.2A$	-	5.5	-	V

¹ $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

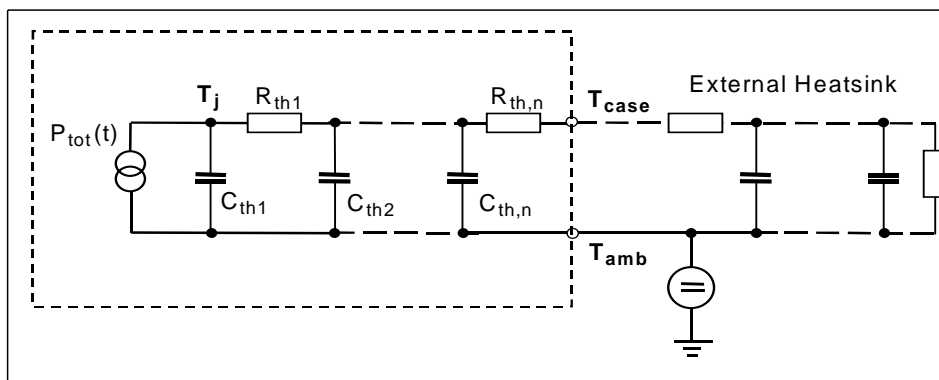
² $C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

Electrical Characteristics, at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Characteristics						
Inverse diode continuous forward current	I_S	$T_C=25^\circ\text{C}$	-	-	3.2	A
Inverse diode direct current, pulsed	I_{SM}		-	-	9.6	
Inverse diode forward voltage	V_{SD}	$V_{GS}=0\text{V}, I_F=I_S$	-	1	1.2	V
Reverse recovery time	t_{rr}	$V_R=420\text{V}, I_F=I_S,$	-	250	400	ns
Reverse recovery charge	Q_{rr}	$di_F/dt=100\text{A}/\mu\text{s}$	-	1.8	-	μC
Peak reverse recovery current	I_{rrm}		-	15	-	A
Peak rate of fall of reverse recovery current	di_{rr}/dt		-	-	540	$\text{A}/\mu\text{s}$

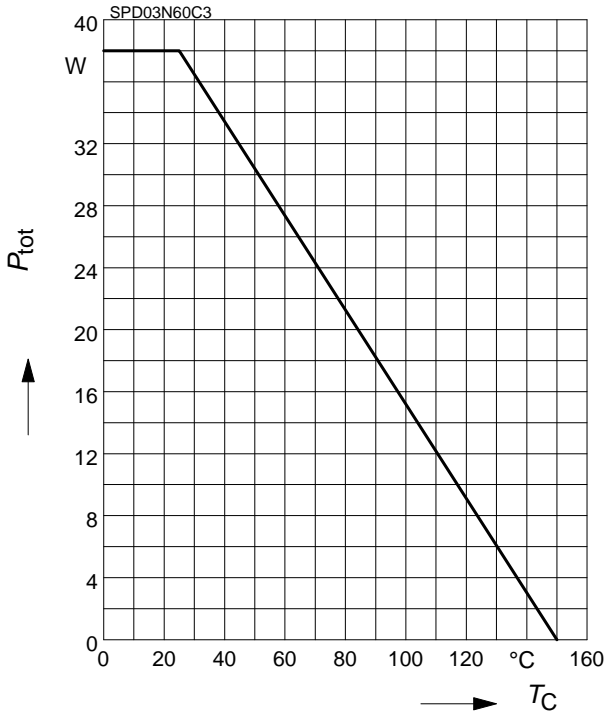
Transient Thermal Characteristics

Symbol	Value	Unit	Symbol	Value	Unit
	typ.			typ.	
Thermal resistance			Thermal capacitance		
R_{th1}	0.054	K/W	C_{th1}	0.00005915	Ws/K
R_{th2}	0.115		C_{th2}	0.0002028	
R_{th3}	0.18		C_{th3}	0.0003548	
R_{th4}	0.361		C_{th4}	0.0008227	
R_{th5}	0.345		C_{th5}	0.004183	
R_{th6}	0.107		C_{th6}	0.046	



1 Power dissipation

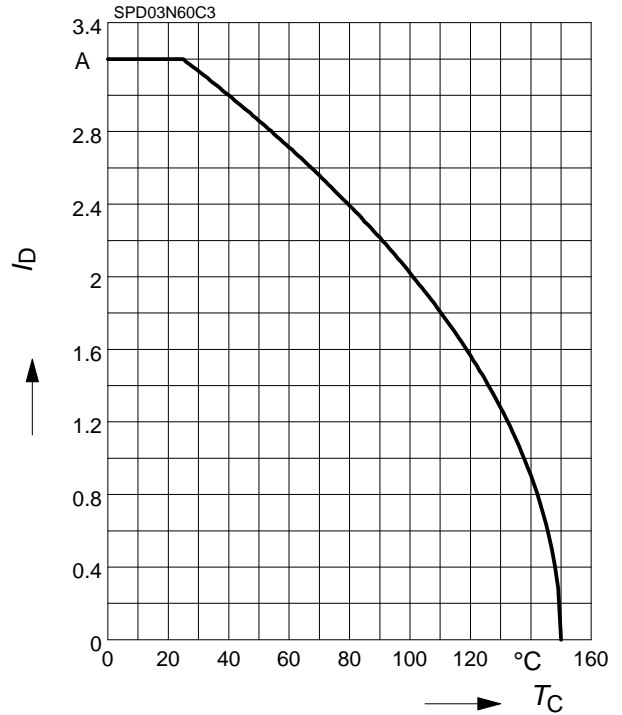
$$P_{\text{tot}} = f(T_C)$$



2 Drain current

$$I_D = f(T_C)$$

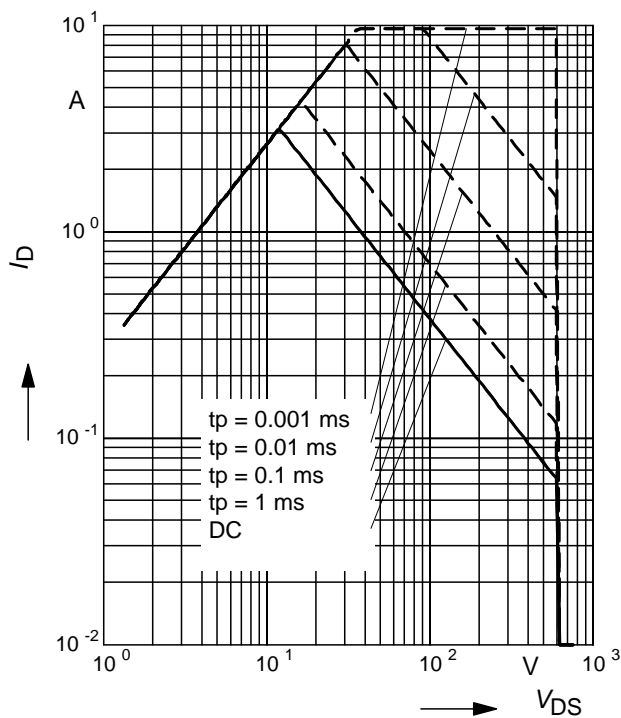
parameter: $V_{GS} \geq 10 \text{ V}$



3 Safe operating area

$$I_D = f(V_{DS})$$

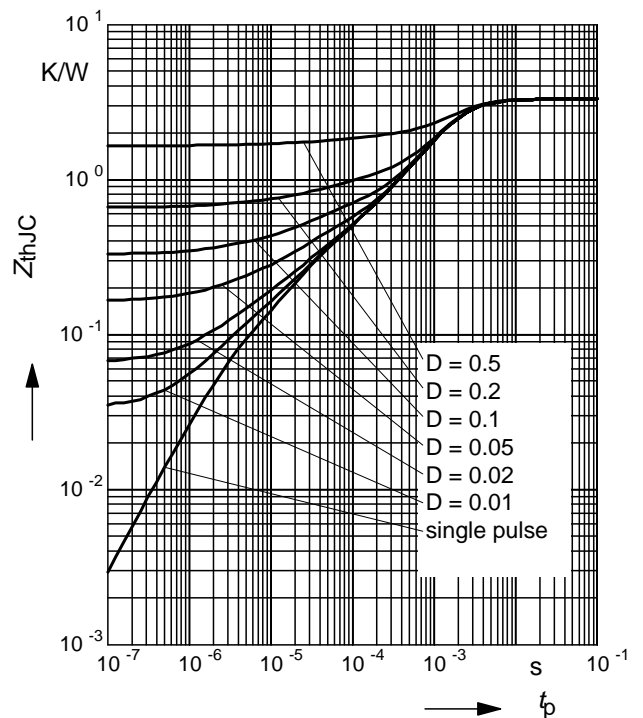
parameter: $D = 0$, $T_C = 25^\circ\text{C}$



4 Transient thermal impedance

$$Z_{\text{thJC}} = f(t_p)$$

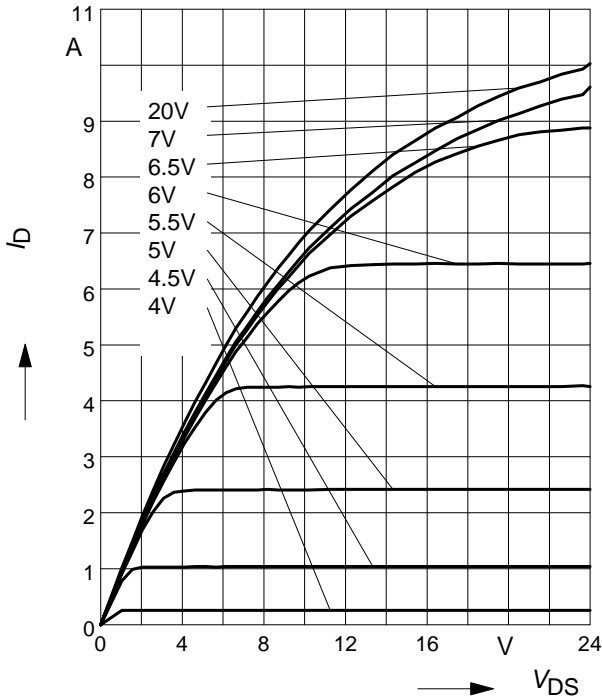
parameter: $D = t_p/T$



5 Typ. output characteristic

$I_D = f(V_{DS}); T_j = 25^\circ\text{C}$

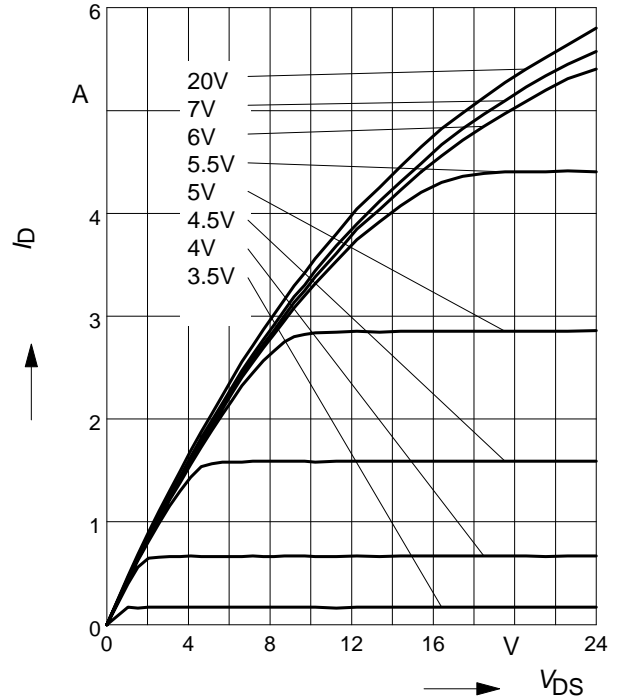
parameter: $t_p = 10 \mu\text{s}, V_{GS}$



6 Typ. output characteristic

$I_D = f(V_{DS}); T_j = 150^\circ\text{C}$

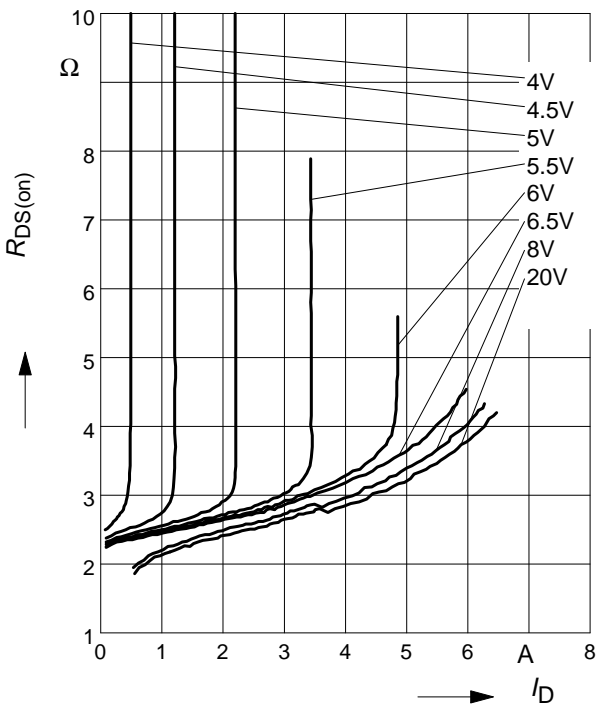
parameter: $t_p = 10 \mu\text{s}, V_{GS}$



7 Typ. drain-source on resistance

$R_{DS(on)} = f(I_D)$

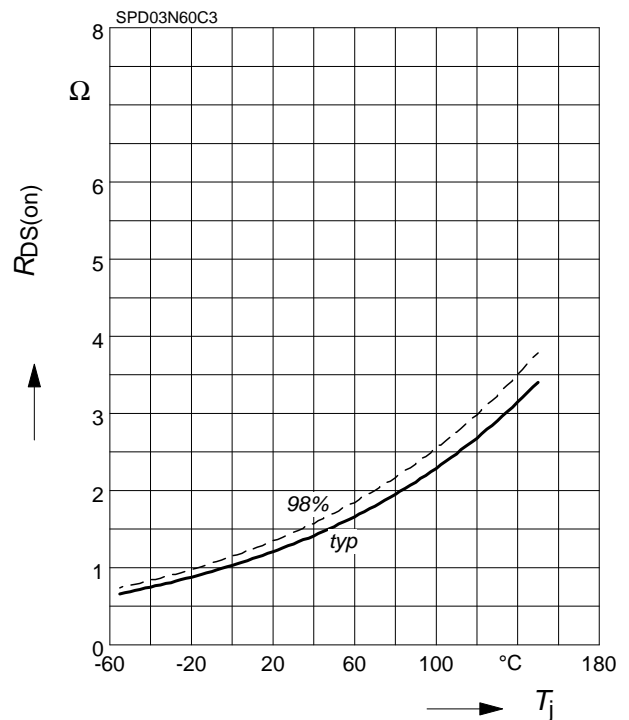
parameter: $T_j = 150^\circ\text{C}, V_{GS}$



8 Drain-source on-state resistance

$R_{DS(on)} = f(T_j)$

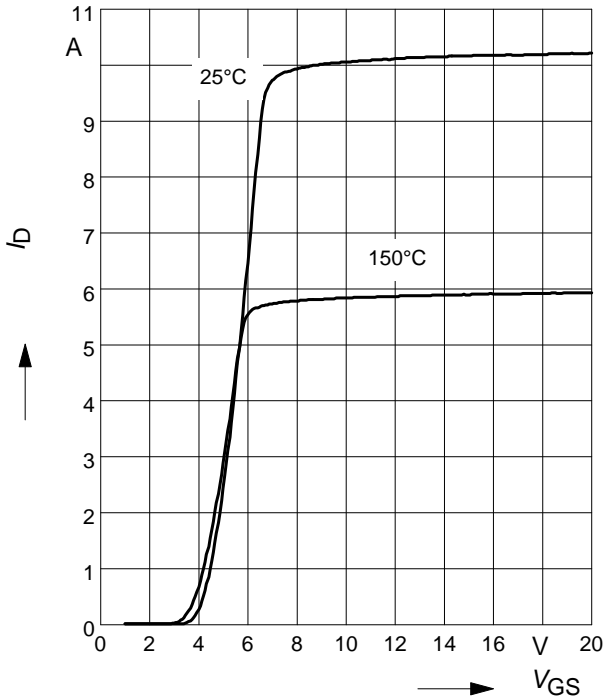
parameter: $I_D = 2 \text{ A}, V_{GS} = 10 \text{ V}$



9 Typ. transfer characteristics

$I_D = f(V_{GS})$; $V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$

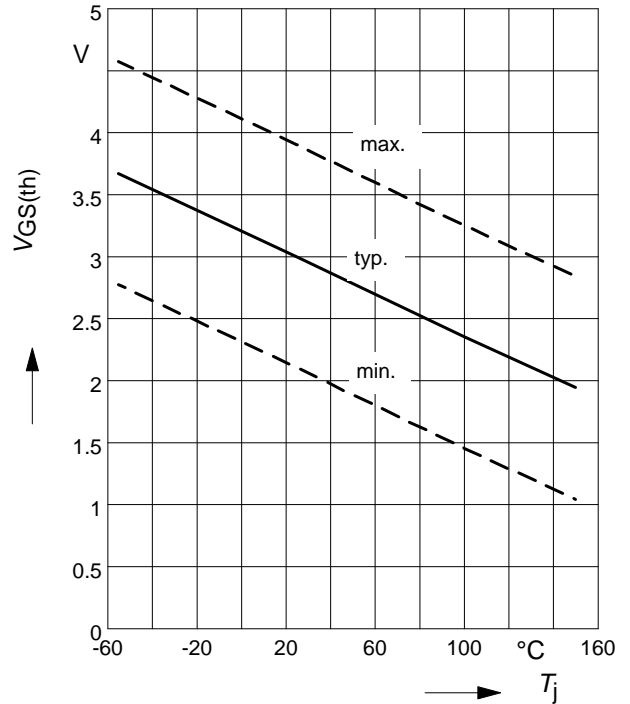
parameter: $t_p = 10 \mu s$



10 Gate threshold voltage

$V_{GS(th)} = f(T_j)$

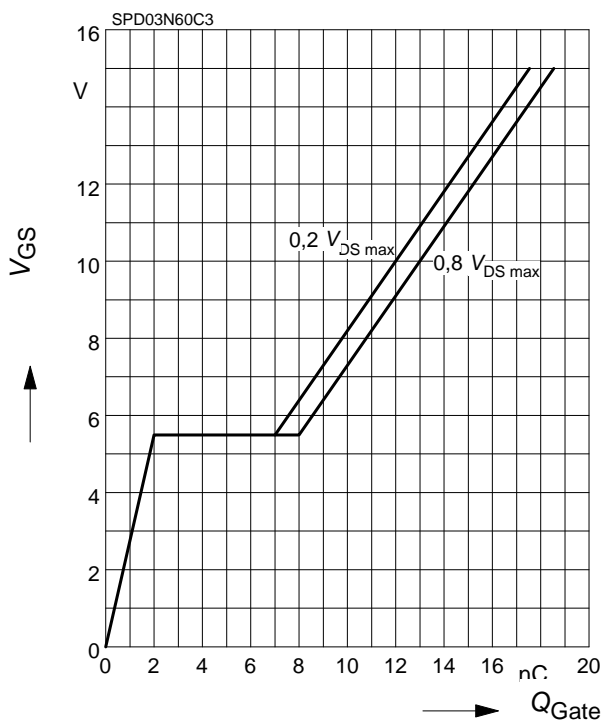
parameter: $V_{GS} = V_{DS}$, $I_D = 135 \mu A$



11 Typ. gate charge

$V_{GS} = f(Q_{Gate})$

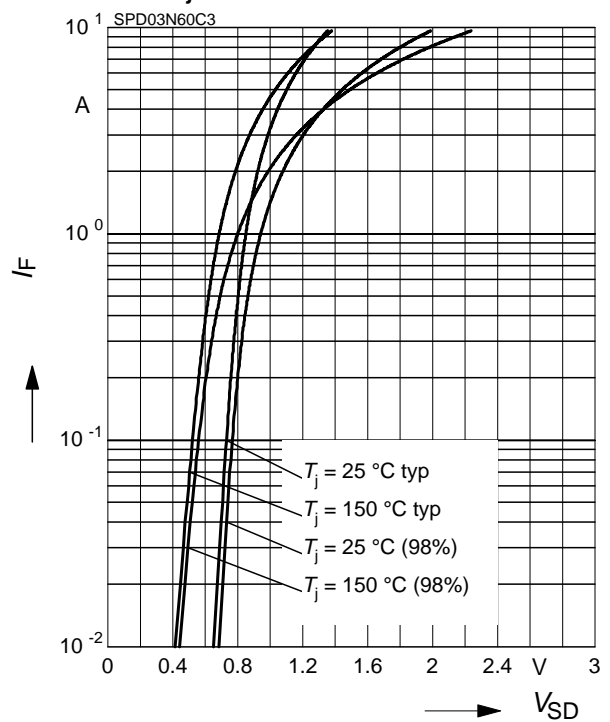
parameter: $I_D = 3.2 A$ pulsed



12 Forward characteristics of body diode

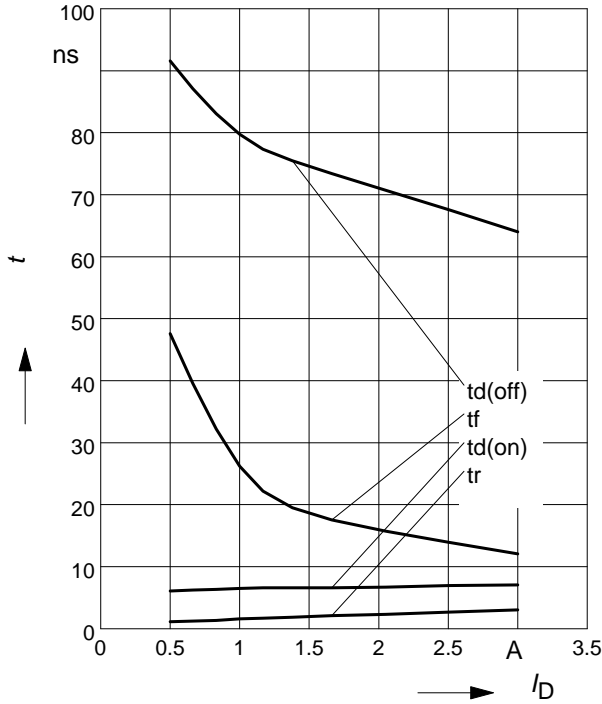
$I_F = f(V_{SD})$

parameter: T_j , $t_p = 10 \mu s$



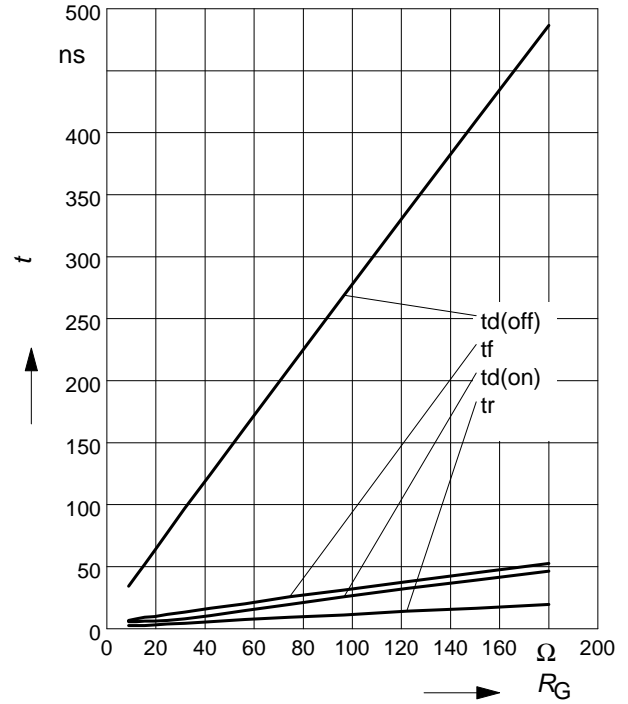
13 Typ. switching time

$t = f(I_D)$, inductive load, $T_j = 125^\circ\text{C}$
par.: $V_{DS} = 380\text{V}$, $V_{GS} = 0/+13\text{V}$, $R_G = 20\Omega$



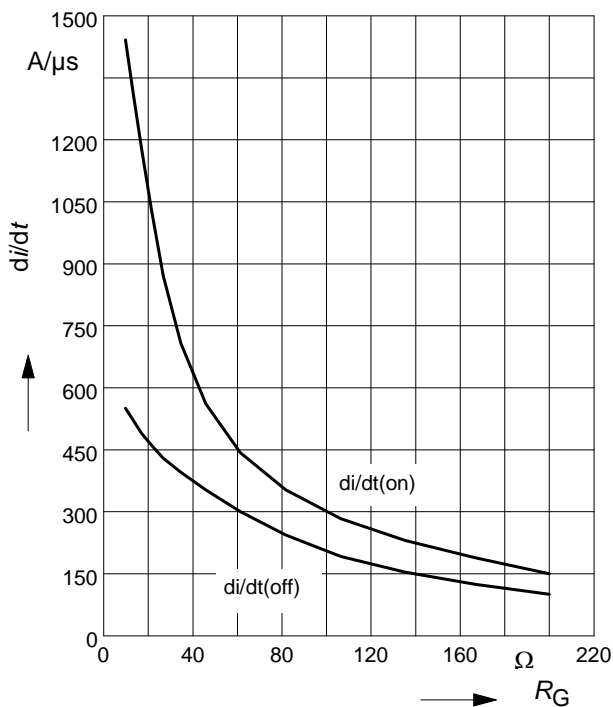
14 Typ. switching time

$t = f(R_G)$, inductive load, $T_j = 125^\circ\text{C}$
par.: $V_{DS} = 380\text{V}$, $V_{GS} = 0/+13\text{V}$, $I_D = 3.2\text{ A}$



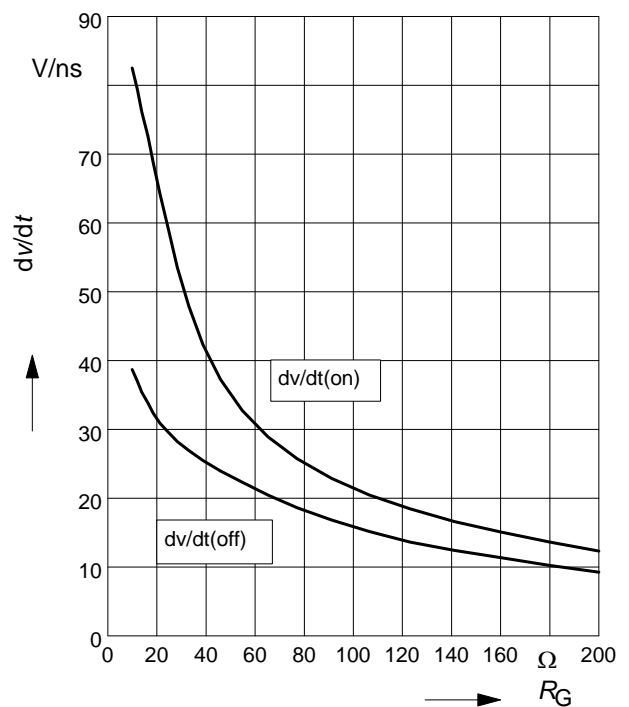
15 Typ. drain current slope

$di/dt = f(R_G)$, inductive load, $T_j = 125^\circ\text{C}$
par.: $V_{DS} = 380\text{V}$, $V_{GS} = 0/+13\text{V}$, $I_D = 3.2\text{ A}$



16 Typ. drain source voltage slope

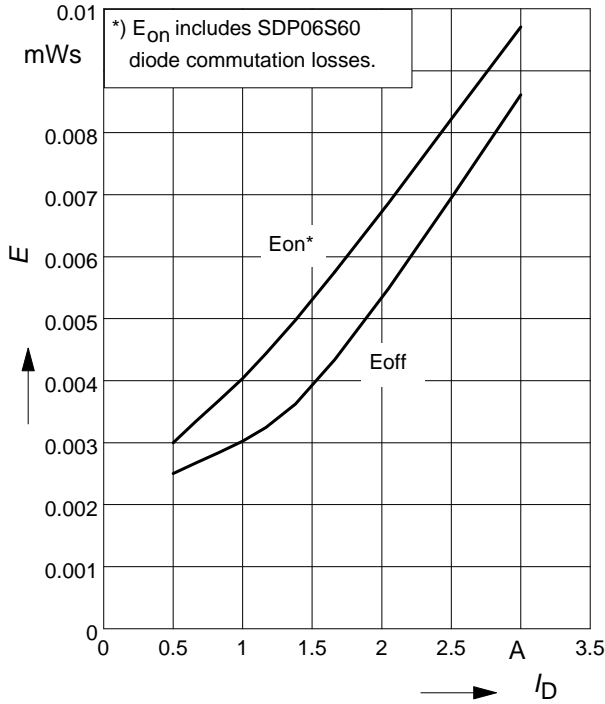
$dv/dt = f(R_G)$, inductive load, $T_j = 125^\circ\text{C}$
par.: $V_{DS} = 380\text{V}$, $V_{GS} = 0/+13\text{V}$, $I_D = 3.2\text{ A}$



17 Typ. switching losses

$E = f(I_D)$, inductive load, $T_j = 125^\circ\text{C}$

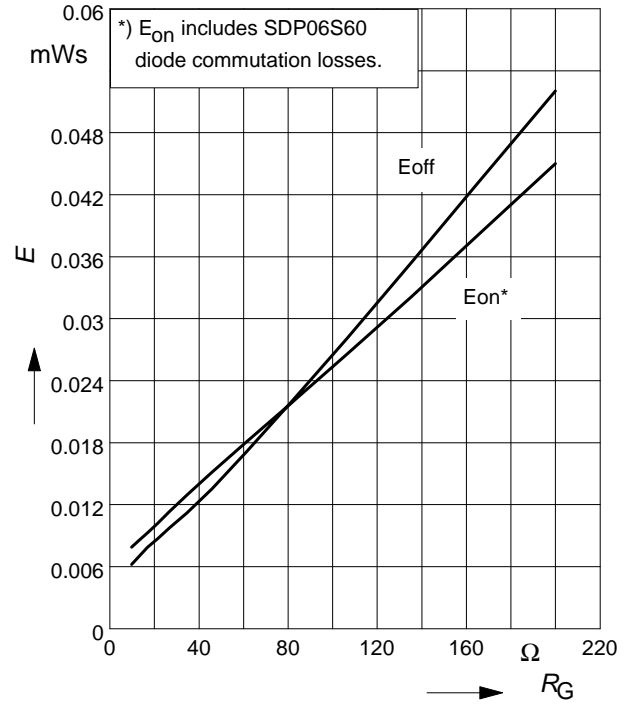
par.: $V_{DS} = 380\text{V}$, $V_{GS} = 0/+13\text{V}$, $R_G = 20\Omega$



18 Typ. switching losses

$E = f(R_G)$, inductive load, $T_j = 125^\circ\text{C}$

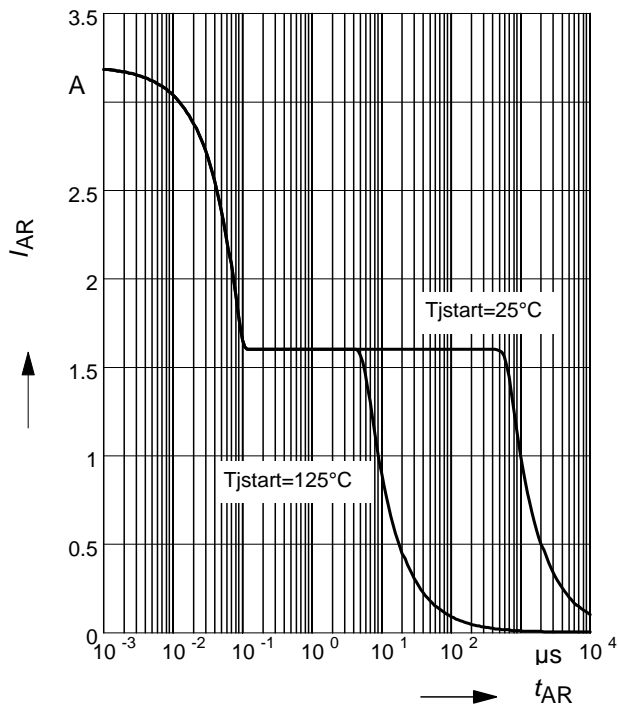
par.: $V_{DS} = 380\text{V}$, $V_{GS} = 0/+13\text{V}$, $I_D = 3.2\text{A}$



19 Avalanche SOA

$I_{AR} = f(t_{AR})$

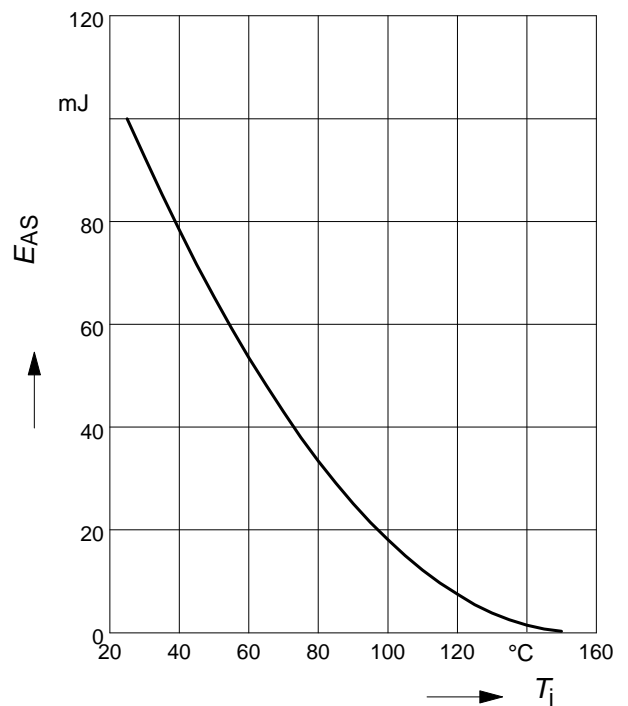
par.: $T_j \leq 150^\circ\text{C}$



20 Avalanche energy

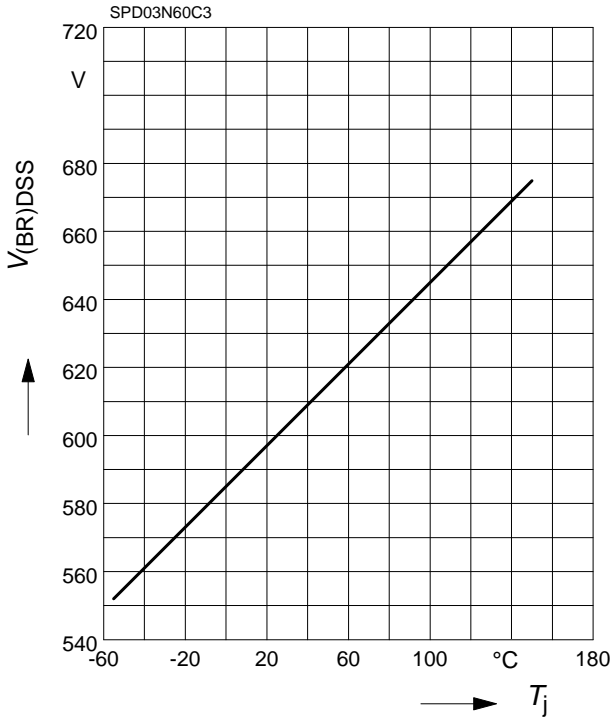
$E_{AS} = f(T_j)$

par.: $I_D = 1.6\text{A}$, $V_{DD} = 50\text{V}$



21 Drain-source breakdown voltage

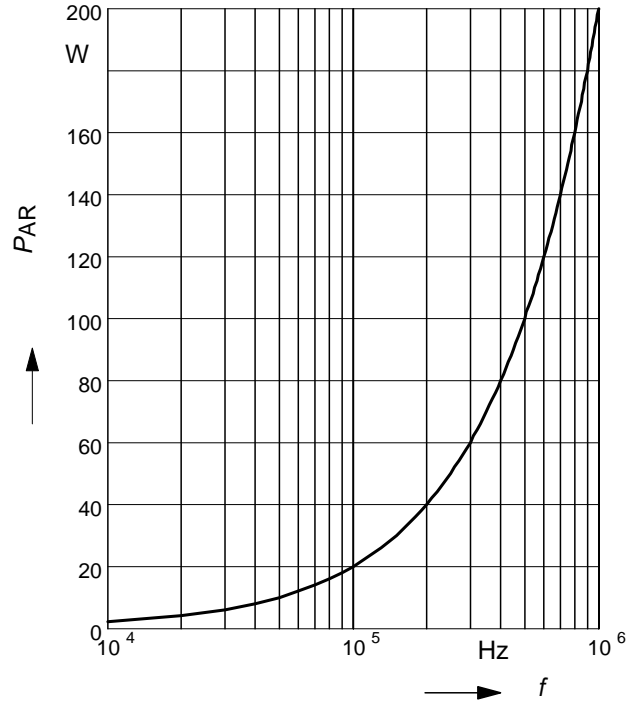
$$V_{(BR)DSS} = f(T_j)$$



22 Avalanche power losses

$$P_{AR} = f(f)$$

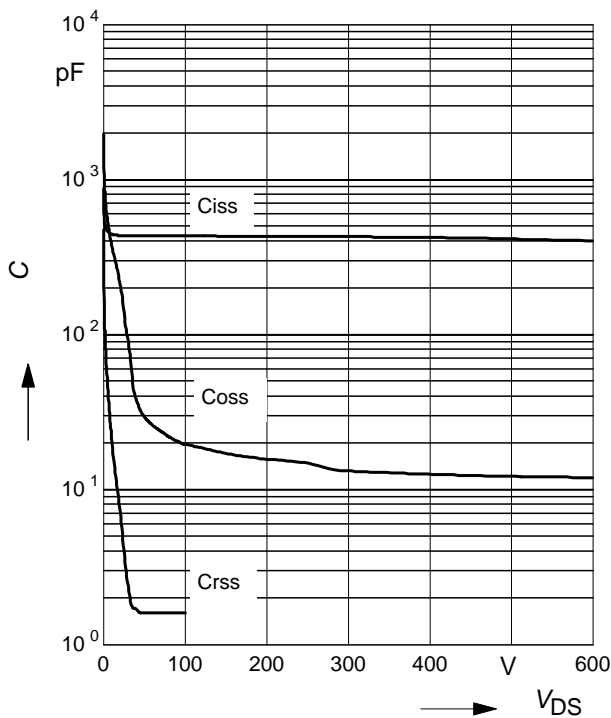
parameter: $E_{AR}=0.2mJ$



23 Typ. capacitances

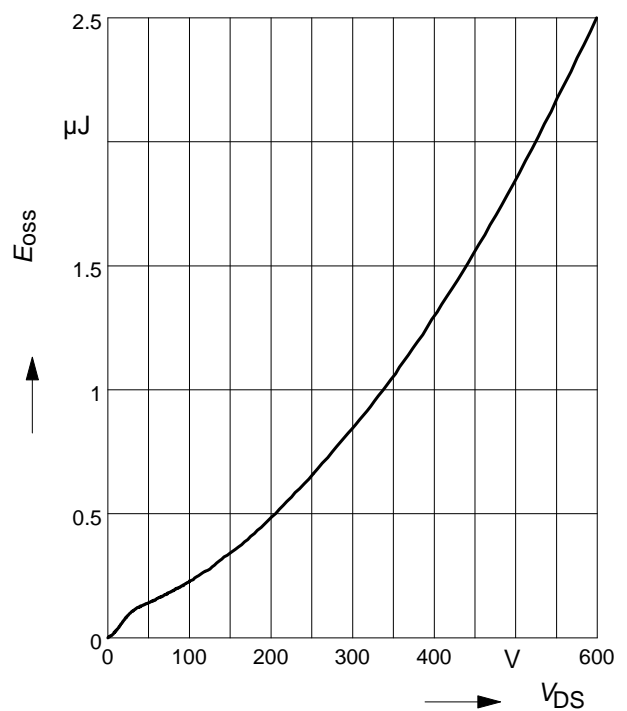
$$C = f(V_{DS})$$

parameter: $V_{GS}=0V, f=1 MHz$

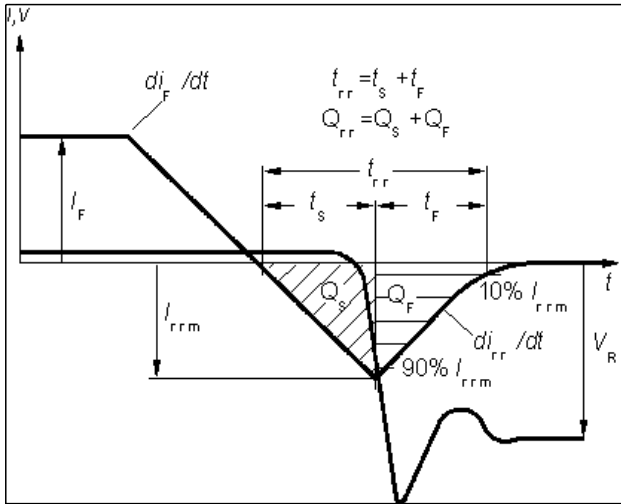


24 Typ. C_{OSS} stored energy

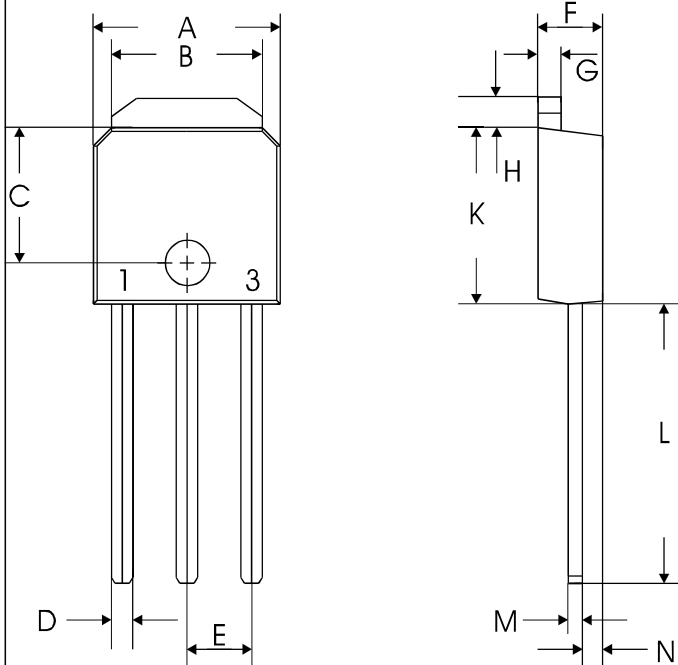
$$E_{OSS}=f(V_{DS})$$



Definition of diodes switching characteristics

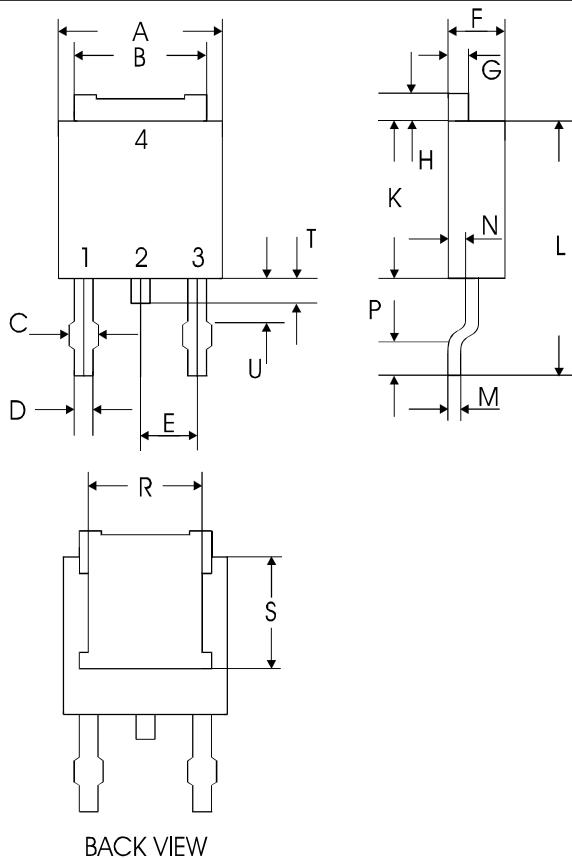


P-TO251 (I-Pak)



symbol	dimensions			
	[mm]		[inch]	
	min	max	min	max
A	6.47	6.73	0.2547	0.2650
B	5.25	5.41	0.2067	0.2130
C	4.19	4.43	0.1650	0.1744
D	0.63	0.89	0.0248	0.0350
E	2.29 typ.		0.0902 typ.	
F	2.18	2.39	0.0858	0.0941
G	0.76	0.86	0.0299	0.0339
H	1.01	1.11	0.0398	0.0437
K	5.97	6.23	0.2350	0.2453
L	9.14	9.65	0.3598	0.3799
M	0.46	0.56	0.0181	0.0220
N	0.98	1.15	0.0386	0.0453

P-TO252 (D-Pak)



symbol	dimensions			
	[mm]		[inch]	
	min	max	min	max
A	6.40	6.73	0.2520	0.2650
B	5.25	5.50	0.2067	0.2165
C	(0.65)	(1.15)	(0.0256)	(0.0453)
D	0.63	0.89	0.0248	0.0350
E	2.28		0.2520	
F	2.19	2.39	0.0862	0.0941
G	0.76	0.98	0.0299	0.0386
H	0.90	1.21	0.0354	0.0476
K	5.97	6.23	0.2350	0.2453
L	9.40	10.40	0.3701	0.4094
M	0.46	0.58	0.0181	0.0228
N	0.87	1.15	0.0343	0.0453
P	0.51	-	0.0201	-
R	5.00	-	0.1969	-
S	4.17	-	0.1642	-
T	0.26	1.02	0.0102	0.0402
U	-	-	-	-

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